

SPECIFICATION

POWER INDUCTOR

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NRS5020 TYPE

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Magnetic Shielded Type

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( 1 / 1 3 )	<b>Specifications</b>
	NRS5020TYPE

**1. Range of application**

This specifications are applied to Power Inductor, NRS5020.

**2. Ordering code**

Example : NRS    5020    T    100    M    □□□  
                  (1)           (2)       (3)       (4)       (5)       (6)

- (1) Type
- (2) External dimensions
- (3) Packing style (T: Tape & Reel)
- (4) Inductance
- (5) Inductance tolerance
- (6) Internal Code

**3. Standard measuring method**

Inductance	: LCR meter	(HP 4285A or equivalent, 100KHz, 1V)
Self-resonant frequency	: Impedance/Material Analyzer	(HP 4291A or equivalent)
DC resistance	: DC Ohmmeter	(HIOKI 3227 or equivalent)

Standard test conditions for electrical characteristics

Unless otherwise specified, temperature is at  $20 \pm 15$  °C and humidity is at  $65 \pm 20$  %.

Should any doubt arise about the test results, further test shall be conducted at a temperature  $20 \pm 2$  °C and humidity  $65 \pm 5$  %.

For inductance, our measured values shall be standard.

**4. Operating temperature range**

$-25$  °C to  $+125$  °C (Including self-heating)

**5. Storage temperature range**

$-40$  °C to  $+85$  °C (For products in unopened tape package,  $-5$  to  $40$ °C)

**6. Electrical characteristics**

Refer to table 1.

**7. External dimensions and structural drawing**

Refer to Table 2.

**8. Mechanical performance**

Refer to Table 3.

**9. Environment test performance specifications**

Refer to Table 3.

**10. Tape and Reel packaging dimensions**

Refer to Table 4.

**11. Packing form**

Refer to Table 5.

**12. Reflow profile chart**

Refer to Table 6.

( 2 / 1 3 )	<b>Table 1</b>	
	ELECTRICAL CHARACTERISTICS	

Ordering Code	Nominal Inductance [ $\mu$ H]	Inductance Tolerance [%]	D.C. Resistance $\pm 20\%$ [ $\Omega$ ]	Rated Current [mA]		Self-resonant Frequency [MHz] min
				Saturation Current Idc1	Temperature Rise current Idc2	
NRS5020T 1R0NMGJ	1.0	$\pm 30$	0.021	4000	3600	81
NRS5020T 1R5NMGJ	1.5	$\pm 30$	0.026	3350	3200	68
NRS5020T 2R2NMGJ	2.2	$\pm 30$	0.035	2900	2900	57
NRS5020T 3R3NMGJ	3.3	$\pm 30$	0.048	2400	2400	46
NRS5020T 4R7MMGJ	4.7	$\pm 20$	0.060	2000	2000	37
NRS5020T 6R8MMGJ	6.8	$\pm 20$	0.090	1600	1650	30
NRS5020T 100MMGJ	10	$\pm 20$	0.120	1300	1450	24
NRS5020T 150MMGJ	15	$\pm 20$	0.165	1100	1200	20
NRS5020T 220MMGJ	22	$\pm 20$	0.260	900	1000	17

\*) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%.  
(at 20°C)

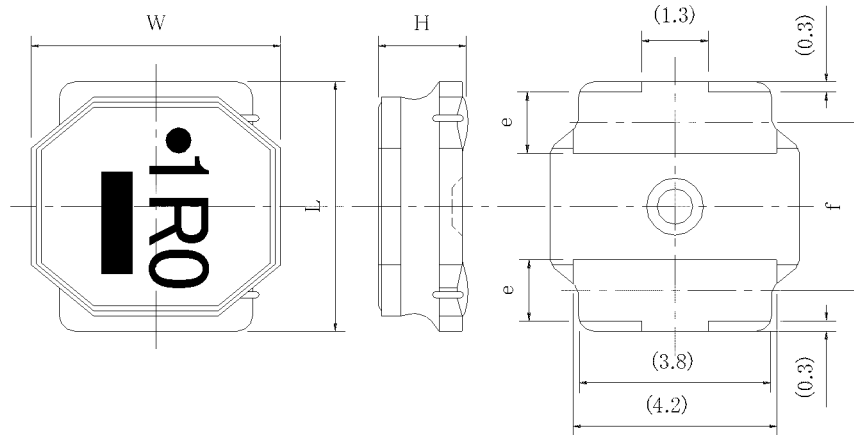
\*) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C.(at 20°C)

\*) The rated current is the DC current value that satisfies both of current saturation current value and temperature rise current value.

Table 2

EXTERNAL DIMENSIONS AND  
STRUCTURAL DRAWING

## 1. External dimensions

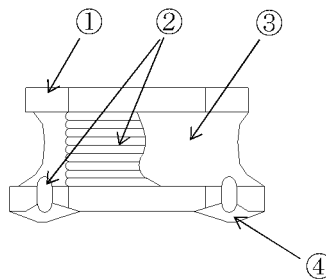


( ) : Reference value

Description	Mark	Dimensions
Length	L	$4.9 \pm 0.2$
Width	W	$4.9 \pm 0.2$
Height	H	2.0MAX
Width of Electrode	e	$1.2 \pm 0.2$
Space between electrodes	f	$3.3 \pm 0.2$

(Unit: mm)

## 2. Structural drawing



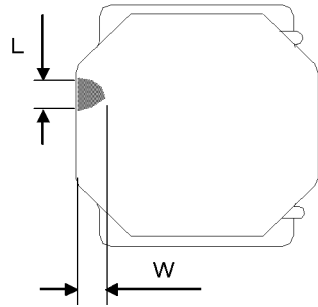
(Magnetic Shielded Type)

① Ferrite core	Ni-Zn ferrite	
② Winding wire	Polyurethane-copper wire	
③ Over-coating resin	Epoxy resin, containing ferrite powder	
④ Electrode	External electrode (substrate)	Ag
	External electrode (base plating)	Ni-Sn
	External electrode (top surface solder coating)	Sn-Ag-Cu

( 4 / 1 3 )	<b>Table 2</b>	
	APPEARANCE TOLERANCE LIMIT AND PRODUCT MARKING	

3. Core chipping

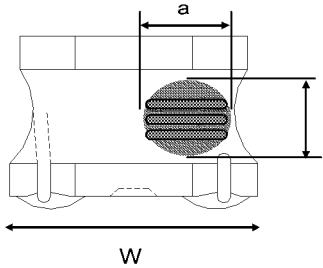
The appearance standard of the chipping size in top side, of bottom side ferrite core is following dimension.



L	W
1.5mm Max.	1.5mmMax.

4. Void appearance tolerance limit

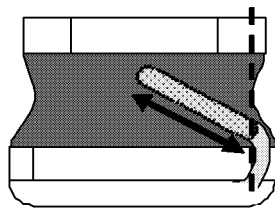
Size of voids occurring to coating resin is specified below.



- ① Width direction (dimension a) : Acceptable when  $a \leq w/2$   
Nonconforming when  $a > w/2$
- ② Length direction (dimension b) : Dimension b is not specified.
- ③ When total area of voids (including one exposing coil) occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

5. External appearance criterion for exposed wire

Exposed end of the winding wire at the secondary side should be 3mm and below.

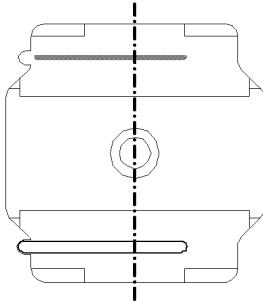


( 5 / 1 3 )	<b>Table 2</b>	
	APPEARANCE TOLERANCE LIMIT AND PRODUCT MARKING	

6. Electrode appearance criterion for exposed wire

Cross section of wire joint part

<Appearance judgment>



Upper part of wire is exposed.

Good



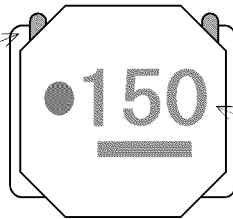
Solder is shed by wire.

Less than 1/2 of joint side length.

It is not covered more than the half of the diameter with solder.

7. Product Marking

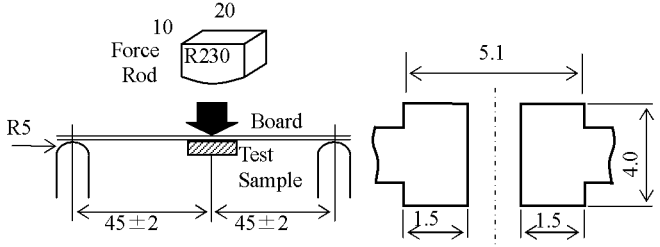
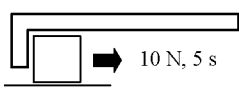
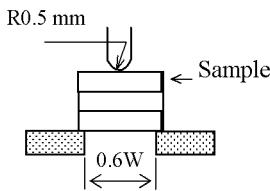
The primary winding side  
(Start of winding)



Product name mark

The left side of the position of the marking is the primary winding side (start of winding).

( 6 / 1 3 )	<b>Table 3</b>	
	MECHANICAL PERFORMANCE / ENVIRONMENTAL TEST PERFORMANCE SPECIFICATIONS	

	Test Item	Standard	Test method
ELECTRICAL CHARACTERISTICS	Inductance	Refer to Table 1.	LCR meter (HP4285A or equivalent)
	DC resistance	Refer to Table 1.	DC ohm meter (HIOKI3227 or equivalent)
	Rated current	Refer to Table 1.	Maximum DC value that does not cause inductance to decrease more than 30% with DC bias and does not cause temperature to increase by more than 40°C.
	Self resonant frequency	Refer to Table 1.	Impedance/material analyzer (HP4291A or equivalent)
MECHANICAL CHARACTERISTICS	Resistance to deflection	No damage.	<p>The test samples shall be soldered to the test board by the reflow soldering conditions show in Table 6. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm.</p>  <p style="text-align: right;">Land dimensions</p> <p>Test board size : 100 × 40 × 1.0            Test board material: glass epoxy-resin            Solder cream thickness: 0.15      Unit: mm</p>
	Adhesion of Terminal electrode	Shall not come off PC board	<p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6.</p>  <p>Applied force: 10 N to X and Y directions.            Duration: 5 s.            Solder cream thickness: 0.15 mm            (Refer to recommended Land Pattern Dimensions defined in "Precaution")</p>
	Body strength	No damage.	<p>Applied force: 30 N            Duration: 10 s</p> 

( 7 / 1 3 )	<b>Table 3</b>
	MECHANICAL PERFORMANCE / ENVIRONMENTAL TEST PERFORMANCE SPECIFICATIONS

ENVIRONMENT TESTS	Test Item	Standard	Test method														
	Resistance to vibration	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. Then it shall be submitted to below test conditions. <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td>Frequency range</td> <td>10Hz ~55 Hz</td> </tr> <tr> <td>Total Amplitude</td> <td>1.5 mm (May not exceed acceleration <math>196 \text{ m/S}^2</math>)</td> </tr> <tr> <td>Sweeping Method</td> <td>10Hz to 55Hz to 10 Hz for 1 min.</td> </tr> <tr> <td>Time</td> <td>For 2 hours on each X, Y, and Z axis.</td> </tr> </table>	Frequency range	10Hz ~55 Hz	Total Amplitude	1.5 mm (May not exceed acceleration $196 \text{ m/S}^2$ )	Sweeping Method	10Hz to 55Hz to 10 Hz for 1 min.	Time	For 2 hours on each X, Y, and Z axis.						
	Frequency range	10Hz ~55 Hz															
	Total Amplitude	1.5 mm (May not exceed acceleration $196 \text{ m/S}^2$ )															
	Sweeping Method	10Hz to 55Hz to 10 Hz for 1 min.															
	Time	For 2 hours on each X, Y, and Z axis.															
Resistance to soldering heat (Reflow)	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	The test sample shall be exposed to reflow oven at $230 \pm 5 \text{ }^\circ\text{C}$ for 40 seconds, with peak temperature at $260 \pm 5 \text{ }^\circ\text{C}$ for 5 seconds, 2 times.  Test board thickness: 1.0 mm Test board material: glass epoxy-resin															
Solderability	At least 90 % of surface of terminal electrode is covered by new solder.	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25 %. <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td>Solder Temperature</td> <td><math>245 \pm 5 \text{ }^\circ\text{C}</math></td> </tr> <tr> <td>Time</td> <td><math>5 \pm 1.0 \text{ s.}</math></td> </tr> <tr> <td>Immersing Speed</td> <td>25 mm/s</td> </tr> </table>	Solder Temperature	$245 \pm 5 \text{ }^\circ\text{C}$	Time	$5 \pm 1.0 \text{ s.}$	Immersing Speed	25 mm/s									
Solder Temperature	$245 \pm 5 \text{ }^\circ\text{C}$																
Time	$5 \pm 1.0 \text{ s.}$																
Immersing Speed	25 mm/s																
Temperature characteristics	$\Delta L/L \rightarrow$ within $\pm 20\%$ No abnormality observed in appearance.	Measurement of inductance shall be taken at temperature range within $-25 \text{ }^\circ\text{C}$ to $+85 \text{ }^\circ\text{C}$ . With reference to inductance value at $+20 \text{ }^\circ\text{C}$ , change rate shall be calculated.															
Thermal shock	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.  Conditions of steps for 1 cycle <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Step</th> <th>Temperature</th> <th>Time (min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td><math>-40 \pm 3 \text{ }^\circ\text{C}</math></td> <td><math>30 \pm 3</math></td> </tr> <tr> <td>2</td> <td>Room Temp.</td> <td>3 maximum</td> </tr> <tr> <td>3</td> <td><math>85 \pm 2 \text{ }^\circ\text{C}</math></td> <td><math>30 \pm 3</math></td> </tr> <tr> <td>4</td> <td>Room Temp</td> <td>3 maximum</td> </tr> </tbody> </table>	Step	Temperature	Time (min)	1	$-40 \pm 3 \text{ }^\circ\text{C}$	$30 \pm 3$	2	Room Temp.	3 maximum	3	$85 \pm 2 \text{ }^\circ\text{C}$	$30 \pm 3$	4	Room Temp	3 maximum
Step	Temperature	Time (min)															
1	$-40 \pm 3 \text{ }^\circ\text{C}$	$30 \pm 3$															
2	Room Temp.	3 maximum															
3	$85 \pm 2 \text{ }^\circ\text{C}$	$30 \pm 3$															
4	Room Temp	3 maximum															
Low temperature life test	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. After that, the test samples shall be placed at test conditions as shown in below table. <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td>Temperature</td> <td><math>-40 \pm 2 \text{ }^\circ\text{C}</math></td> </tr> <tr> <td>Time</td> <td><math>500 + 24 \text{ h}</math></td> </tr> </table>	Temperature	$-40 \pm 2 \text{ }^\circ\text{C}$	Time	$500 + 24 \text{ h}$											
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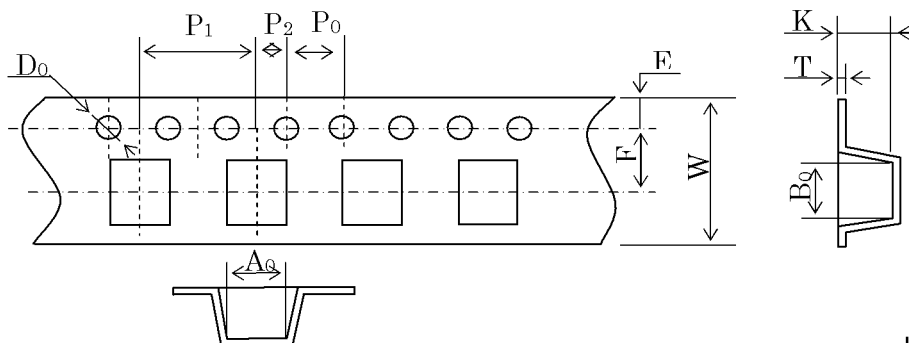
( 8 / 1 3 )	<b>Table 3</b>
	MECHANICAL PERFORMANCE / ENVIRONMENTAL TEST PERFORMANCE SPECIFICATIONS

	Test Item	Standard	Test method							
ENVIRONMENT TESTS	Loading at high temperature life test	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	<p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. The test samples shall be placed in thermostatic oven set at specified temperature and applied the rated current continuously as shown in below table. (※ Notice 1)</p> <table border="1"> <tr> <td>Temperature</td> <td><math>85 \pm 2 \text{ }^\circ\text{C}</math></td> </tr> <tr> <td>Applied current</td> <td>Rated current (Refer to Table 1)</td> </tr> <tr> <td>Time</td> <td><math>500 + 24 \text{ h}</math></td> </tr> </table>	Temperature	$85 \pm 2 \text{ }^\circ\text{C}$	Applied current	Rated current (Refer to Table 1)	Time	$500 + 24 \text{ h}$	
	Temperature	$85 \pm 2 \text{ }^\circ\text{C}$								
	Applied current	Rated current (Refer to Table 1)								
Time	$500 + 24 \text{ h}$									
Damp heat life test	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	<p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table. (※ Notice 1)</p> <table border="1"> <tr> <td>Temperature</td> <td><math>60 \pm 2 \text{ }^\circ\text{C}</math></td> </tr> <tr> <td>Humidity</td> <td>90~95 %RH</td> </tr> <tr> <td>Time</td> <td><math>500 + 24 \text{ h}</math></td> </tr> </table>	Temperature	$60 \pm 2 \text{ }^\circ\text{C}$	Humidity	90~95 %RH	Time	$500 + 24 \text{ h}$		
Temperature	$60 \pm 2 \text{ }^\circ\text{C}$									
Humidity	90~95 %RH									
Time	$500 + 24 \text{ h}$									
Loading under damp heat life test	$\Delta L/L \rightarrow$ within $\pm 10\%$ No abnormality observed in appearance.	<p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table. (※ Notice 1)</p> <table border="1"> <tr> <td>Temperature</td> <td><math>60 \pm 2 \text{ }^\circ\text{C}</math></td> </tr> <tr> <td>Humidity</td> <td>90~95 %RH</td> </tr> <tr> <td>Applied current</td> <td>Rated current (Refer to Table 1)</td> </tr> <tr> <td>Time</td> <td><math>500 + 24 \text{ h}</math></td> </tr> </table>	Temperature	$60 \pm 2 \text{ }^\circ\text{C}$	Humidity	90~95 %RH	Applied current	Rated current (Refer to Table 1)	Time	$500 + 24 \text{ h}$
Temperature	$60 \pm 2 \text{ }^\circ\text{C}$									
Humidity	90~95 %RH									
Applied current	Rated current (Refer to Table 1)									
Time	$500 + 24 \text{ h}$									

Standard measuring condition	Unless otherwise specified, the test samples are placed at room temperature and humidity and measured within 48 hours after exposure to test conditions.
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( 9 / 1 3 )	<b>Table 4</b>
	TAPE & REEL PACKAGING DIMENSIONS

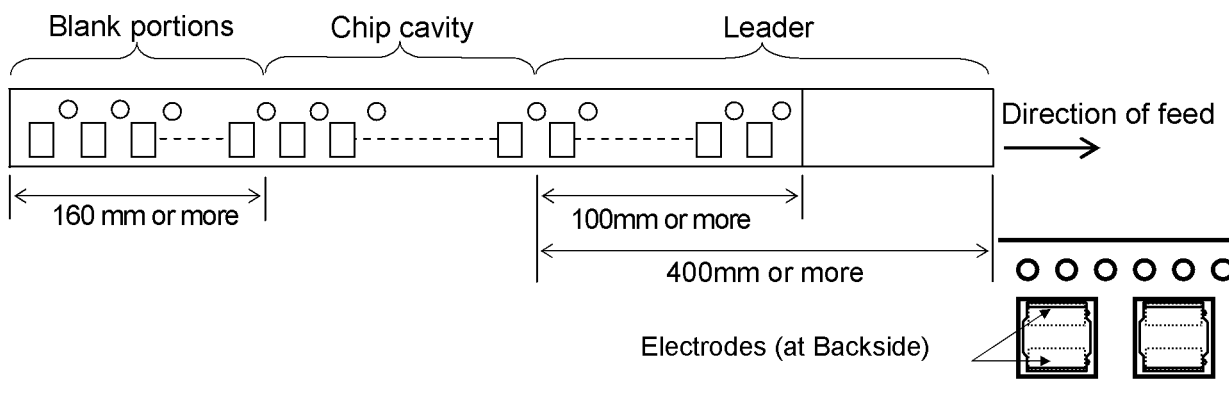
**1. Dimensions**



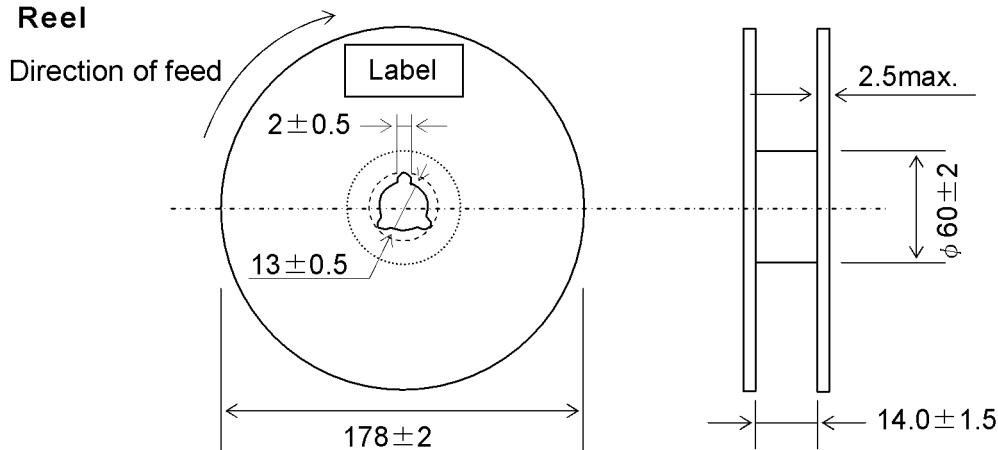
Unit: mm

A <sub>0</sub>	B <sub>0</sub>	W	F	E	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	D <sub>0</sub>	T	K
5.25 ±0.1	5.25 ±0.1	12.0 ±0.3	5.5 ±0.1	1.75 ±0.1	8.0 ±0.1	2.0 ±0.1	4.0 ±0.1	φ 1.5 +0.1 -0	0.3 ±0.1	2.3 ±0.1

**2. Direction of rolling**



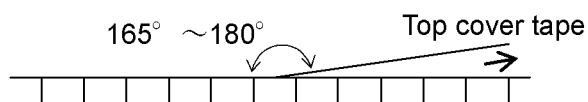
**3. Reel**



Unit: mm

Label position: On the opposite side of sprocket holes side of reel

**4. Top tape strength**



- Peel-off strength : 0.1 N ~ 1.3 N
- Peel-off angle : 165° ~ 180°
- Peel-off speed : 300 mm/min

( 1 0 / 1 3 )	<b>Table 5</b>
	PACKING FORM

**1. The number of components**

A tape & reel package contains 800 inductors.

**2. Tape and Reel**

Emboss carrier tape: 12mm-width and 8 mm-pitch

Reel: 180 mm-diameter

**3. The allowable number of empty chip cavities**

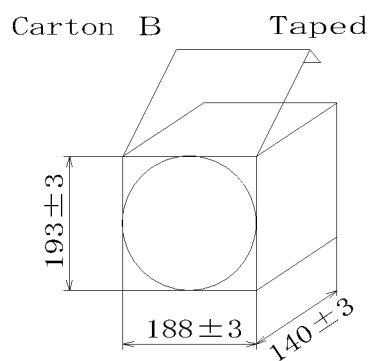
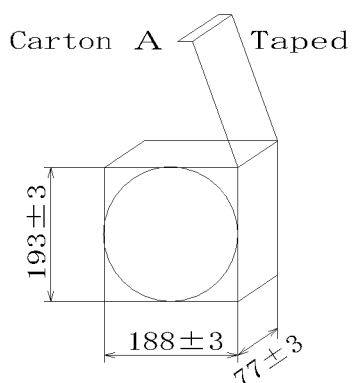
Maximum two (2) chip cavities missing product may exist in a reel but they may not be consecutive two cavities.

**4. Marking**

The following items shall be marked legibly on per tape & reel package.

- (1) Part number of Taiyo Yuden Co., Ltd.
- (2) Supplier name (Taiyo Yuden Co., Ltd.)
- (3) Lot number
- (4) Date (stamp)
- (5) The number of components packed in a reel

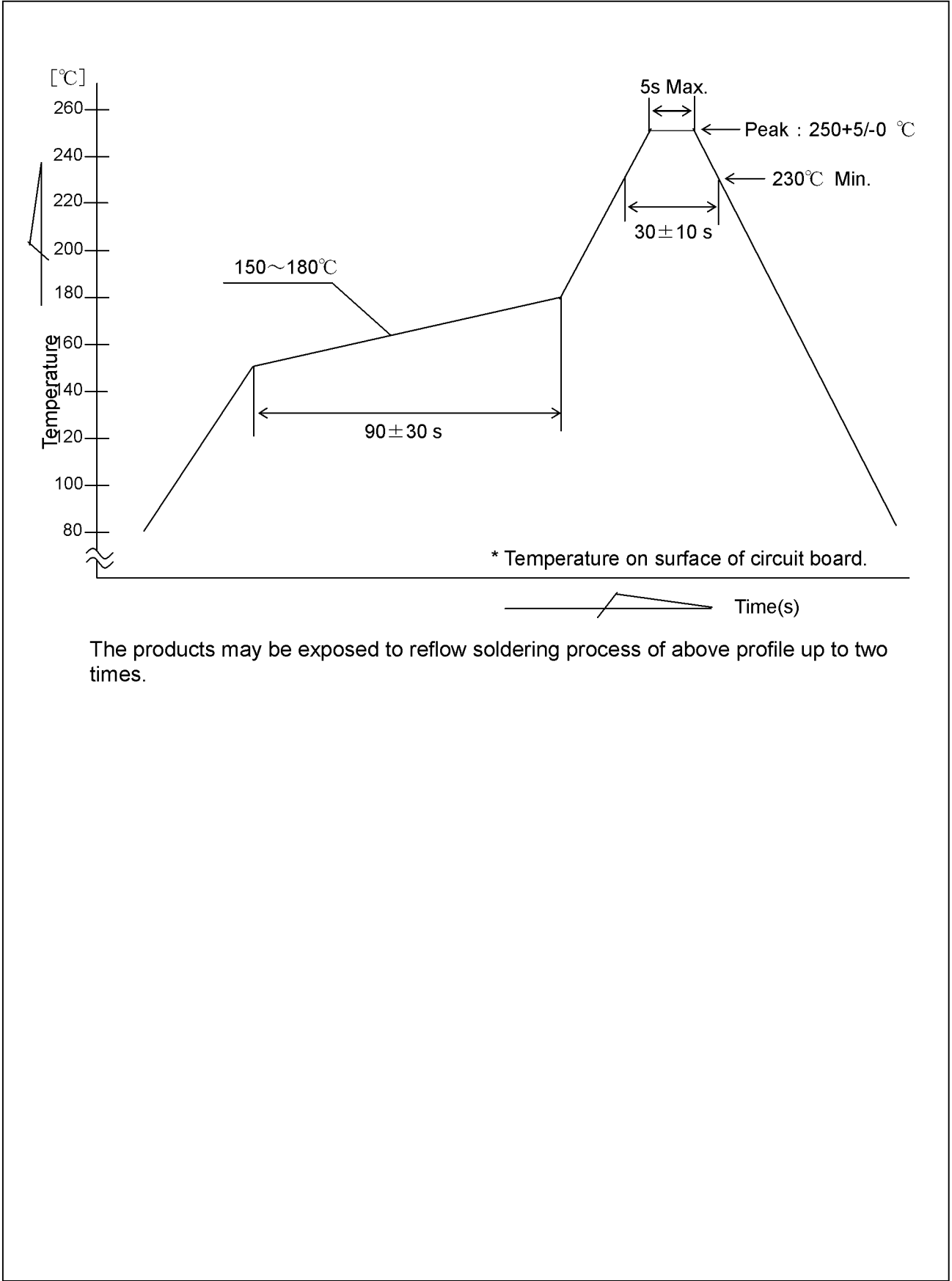
**5. Dimensions of packing box (for Tape & Reel package)**



(Unit: mm)

Number of products 1reel	Maximum number in a carton	
	Carton A	Carton B
800 pcs/1 reel	3200 pcs/4 reel	6400 pcs/8 reel

( 11 / 13 )	<b>Table 6</b>
	REFLOW PROFILE CHART (REFERENCE)

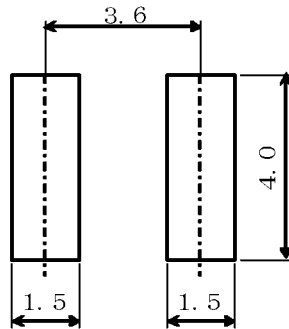


The products may be exposed to reflow soldering process of above profile up to two times.

## Precautions

### 1. Surface Mounting

- Mounting and soldering conditions should be checked beforehand.
- Applicable soldering process to this products is reflow soldering only.
- Recommended Land-Pattern :



(Unit: mm)

### 2. Handling

- Keep the products away from all magnets and magnetic objects.
- Be careful not to subject the products to excessive mechanical shocks.
- Please avoid applying impact to the products after mounted on pc board.
- Avoid ultrasonic cleaning.

### 3. Storage

To prevent deterioration of the solderability of terminal electrodes and/or the packing materials of the products, please store the products under following storage conditions.

Ambient temperature range      0°C to 40 °C

Humidity                                70 % RH maximum

Even under the ideal storage conditions, solderability of inductor's electrode deteriorates as time passes.

### 4. Regarding Regulations

- Any Class- I or Class- II ozone-depleting substance (ODS) listed in the Clean Air Act in US for regulation is not included in the products or applied to the products at any stage of whose manufacturing processes.
- Certain brominated flame retardants (PBBs, PBDEs) are not used at all.
- The products of this specifications are not subject to the Export Trade Control Order in Japan or the Export Administration Regulations in US.

### 5. RoHS compliance

This product conforms to "RoHS compliance".

### 6. Production Sites and country of origin

TAIYO YUDEN (PHILIPPINES) INC.

( 13 / 13 )	<b>Precautions</b>	
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## 7. Guarantee

The guaranteed operating conditions of the products are in accordance with the conditions specified in this specifications.

Please note that Taiyo Yuden Co., Ltd. takes no responsibility for any failure and/or abnormality which is caused by use under other than the aforesaid operating conditions.

### SPECIAL NOTICE

■ All of the contents specified here are subject to change without notice due to technical improvements, etc. Therefore, please check latest version of the components specifications carefully before practical application or usage of the components. Please note that Taiyo Yuden Co., Ltd. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification or individual specification.

■ Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.

■ All electronic components in this specification are developed, designed and intended for use in general electronics equipment. (for Av, office automation, household, office supply, information service, telecommunications, (such as mobile phone or PC) etc.).

Before incorporating the components or devices into any equipment in the field such as transportation, (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact Taiyo Yuden Co., Ltd. for more detail in advance.

Do not incorporate the products into any equipment in fields such as aerospace, aviation, unclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

■ The contents of this specification are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN's official sales channel").

It is only applicable to the products purchased from any of TAIYO YUDEN's official sales channel.

■ Please note that Taiyo Yuden Co., Ltd. shall have no responsibility for any controversies or disputes that may occur in connection with a third party's intellectual property rights and other related rights arising from your usage of products in this specification. Taiyo Yuden Co., Ltd. grants no license for such rights.